

WIREBONDS STATUS													
dE				E-front				E-back				Last checked	
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	date	detector
1				1				1				10/2/07	dE, Ef, Eb
2				2				2					
3				3				3					
4				4				4					
5				5				5					
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28				28				28					
29				29				29					
30				30				30					
31				31				31					
32				32	GR	X	X	32					

Legend:

X = bond missing / = bond broken - = bond damaged

TJ 12

AE = 2297-2
E = 2113-7

(M)

Front Side Data

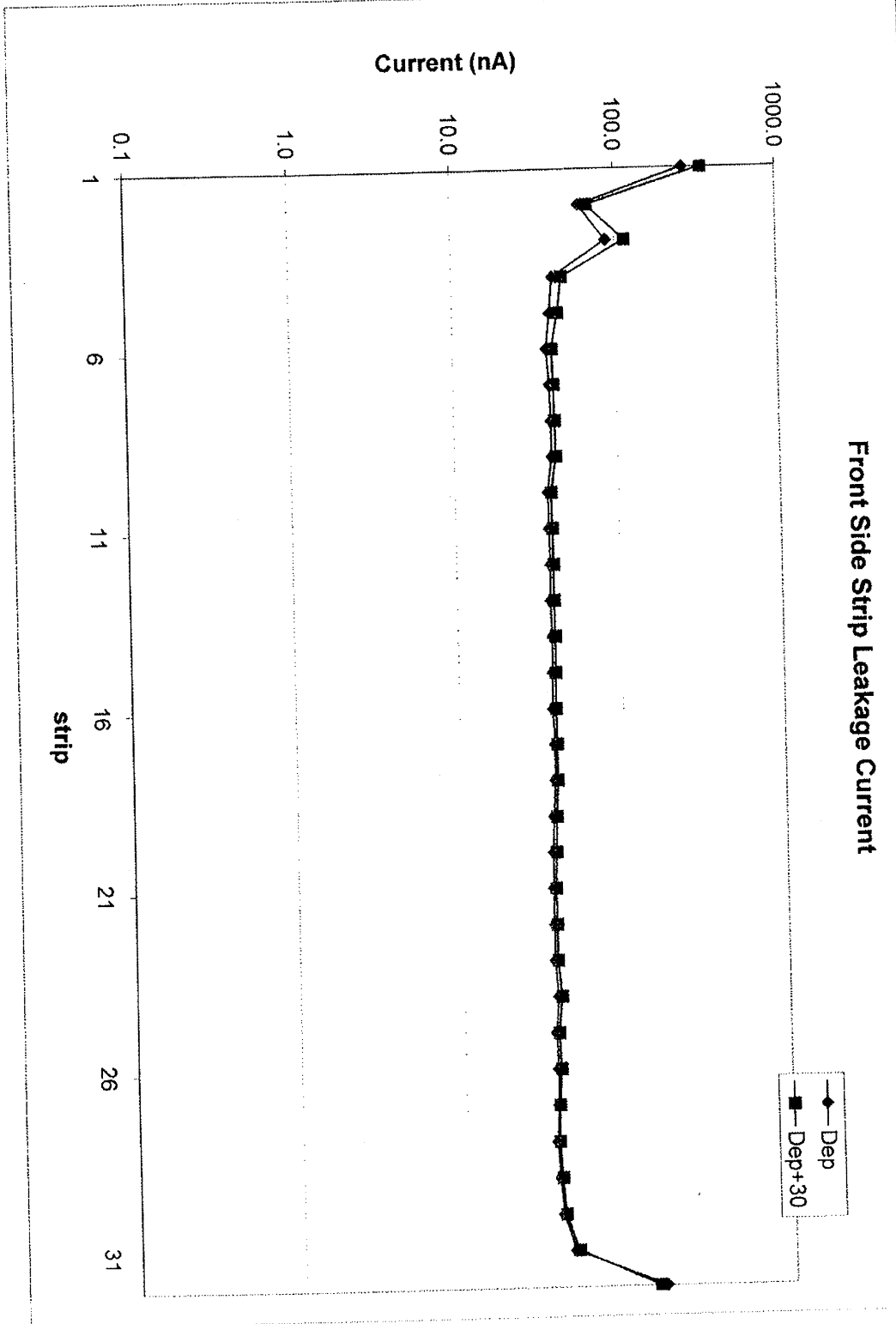
Wafer No. 2113-7

Thickness: 1452 μm

Depletion: 410 Volts

Front Side Strip Leakage Current

S	Current(nA)	Dep	Dep+30
1	268.5	349.7	
2	60.76	68.03	
3	88.61	115.48	
4	41.29	47.05	
5	39.36	44.05	
6	37.22	40.25	
7	38.65	40.77	
8	39.09	41.24	
9	39.03	41.62	
10	36.64	38.53	
11	36.87	38.75	
12	37.32	39.05	
13	36.88	38.82	
14	37.44	39.21	
15	37.14	38.94	
16	36.98	38.72	
17	37.64	39.03	
18	37.47	38.94	
19	36.42	38.04	
20	35.92	37.42	
21	35.56	36.98	
22	35.75	37.26	
23	35.77	37.3	
24	37.13	38.9	
25	35.71	37.26	
26	36.21	37.83	
27	36.32	36.75	
28	35.06	36.26	
29	36.12	37.33	
30	37.58	38.9	
31	43.98	46.04	
32	159.22	145.14	
Total	1623.6	1779.59	



Resolution Plot

HIRA - 1500

Wafer No.: **2113-7**

Thickness: **1452** μm

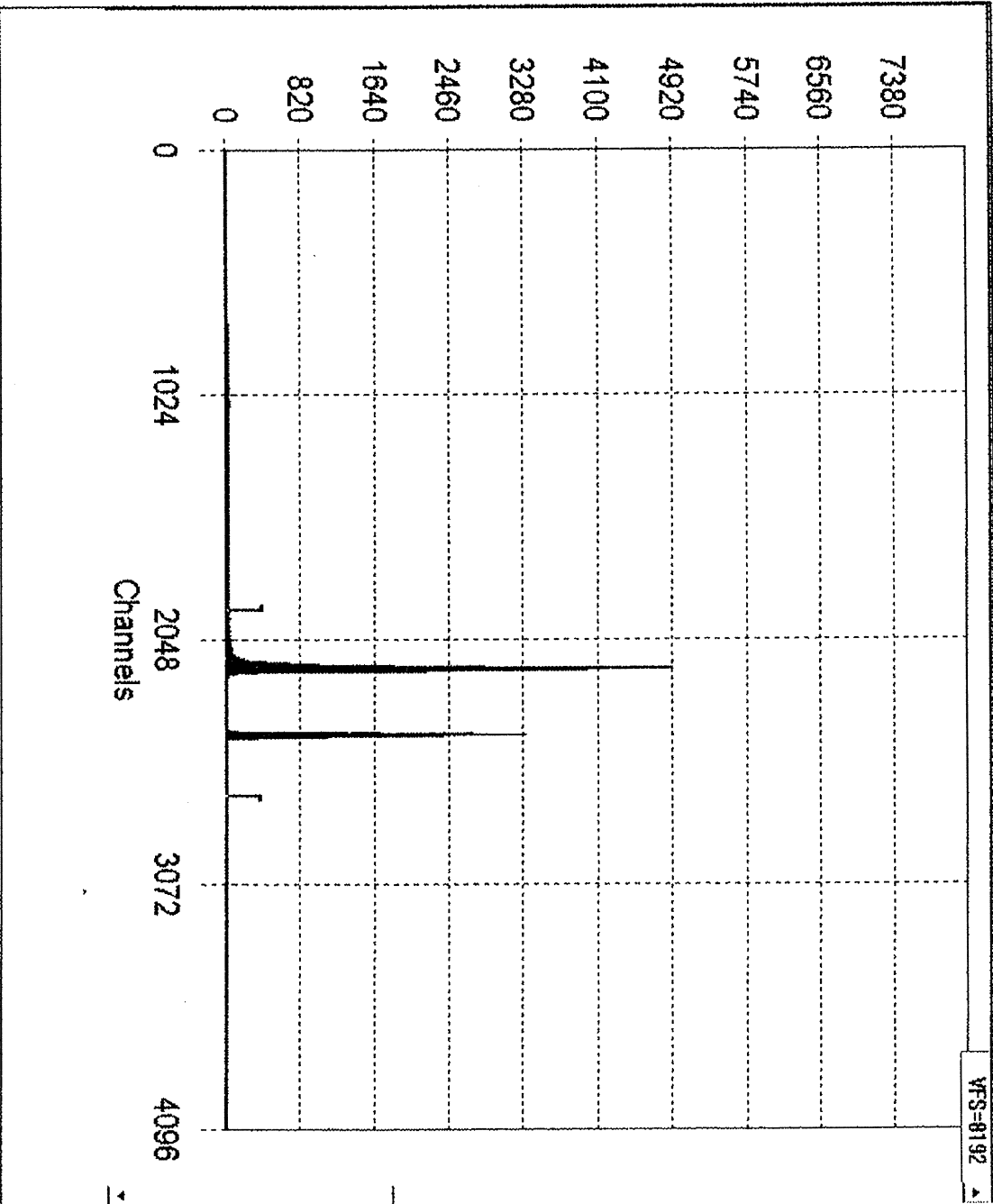
VFS-8192

JUNCTION

DET LINE: **52.1** KeV
SYSTEM: **39** KeV
CAL: **34.5** KeV

OHMIC

DET LINE: **53** KeV
SYSTEM: **38.1** KeV
CALC: **36.8** KeV



BIAS VOLTS= **4.10** V

Leakage **1400** nA

Source
Am 241

Rise Time
1

Flat Top
0

INDIANA UNIVERSITY

BACK RESISTANCE MEASUREMENT:

DATE: 14/05/03
 DEVICE TYPE: HIRA RB7-D/S-1500
 DEVICE NUMBER: 2113-7
 THICKNESS: 1452µM
 OPERATING VOLTAGE: 410V

CHANNEL	OV	V.OP	V.OP + 30V
1-2	1.7KΩ	<1MΩ	<10MΩ
2-3	1.7KΩ	<1MΩ	<10MΩ
3-4	1.7KΩ	<1MΩ	<10MΩ
4-5	1.8KΩ	<1MΩ	<10MΩ
5-6	1.8KΩ	<1MΩ	<10MΩ
6-7	1.8KΩ	<1MΩ	<10MΩ
7-8	1.7KΩ	<1MΩ	<10MΩ
8-9	1.7KΩ	<1MΩ	<10MΩ
9-10	1.7KΩ	<1MΩ	<10MΩ
10-11	1.6KΩ	<1MΩ	<10MΩ
11-12	1.6KΩ	<1MΩ	<10MΩ
12-13	1.5KΩ	<1MΩ	<10MΩ
13-14	1.5KΩ	<1MΩ	<10MΩ
14-15	1.6KΩ	<1MΩ	<10MΩ
15-16	1.6KΩ	<1MΩ	<10MΩ
16-17	1.6KΩ	<1MΩ	<10MΩ
17-18	1.6KΩ	<1MΩ	<10MΩ
18-19	1.6KΩ	<1MΩ	<10MΩ
19-20	1.6KΩ	<1MΩ	<10MΩ
20-21	1.5KΩ	<1MΩ	<10MΩ
21-22	1.6KΩ	<1MΩ	<10MΩ
22-23	1.6KΩ	<1MΩ	<10MΩ
23-24	1.7KΩ	<1MΩ	<10MΩ
24-25	1.7KΩ	<1MΩ	<10MΩ
25-26	1.7KΩ	<1MΩ	<10MΩ
26-27	1.7KΩ	<1MΩ	<10MΩ
27-28	1.7KΩ	<1MΩ	<10MΩ
28-29	1.6KΩ	<1MΩ	<10MΩ
29-30	1.7KΩ	<1MΩ	<10MΩ
30-31	1.2KΩ	<1MΩ	<10MΩ
31-32	1.8KΩ	<1MΩ	<10MΩ

Detector Profile

BB7-1500

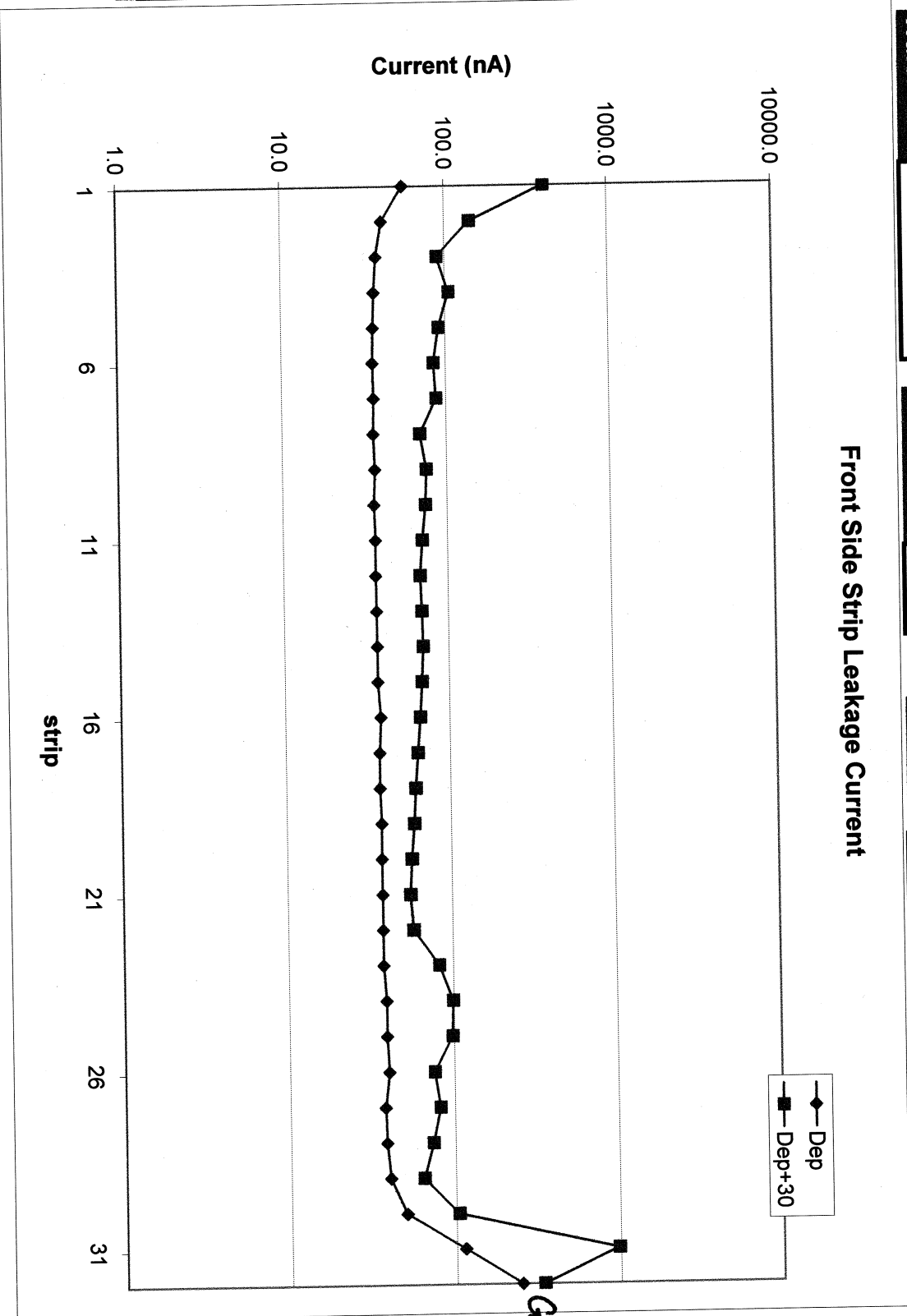
Wafer No.: **2113-7**

Thickness: **1452** μm Vop.

320 Volts

Front Side Data

Strip	Current(nA)	Dep	Dep+30
1	55.6	407.9	
2	41.2	142.4	
3	37.9	89.1	
4	36.6	105.2	
5	36	90.2	
6	35.6	83.5	
7	35.9	86.6	
8	35.5	68.4	
9	36.2	74.4	
10	35.5	73	
11	36.1	69.3	
12	36	66.9	
13	36.2	68.1	
14	36.4	68.7	
15	36.4	67.2	
16	37.7	65.3	
17	36.9	62.8	
18	36.7	60.5	
19	37.4	58.9	
20	37.3	56.5	
21	37.5	55.1	
22	37.5	57.3	
23	37.4	81.5	
24	38.9	98.7	
25	38.9	97.3	
26	39.9	74.9	
27	37.6	80.8	
28	38.2	72.7	
29	40	63.5	
30	50	103.5	
31	113.3	975.6	
32	251.6	343.4	
total	1513.9	3969.2	



Resolution Plot

HIRA BB7

Wafer No.: 2113-7

Thickness: 1452 um

VFS-128

CTION

T LINE: KeV

STEM: KeV

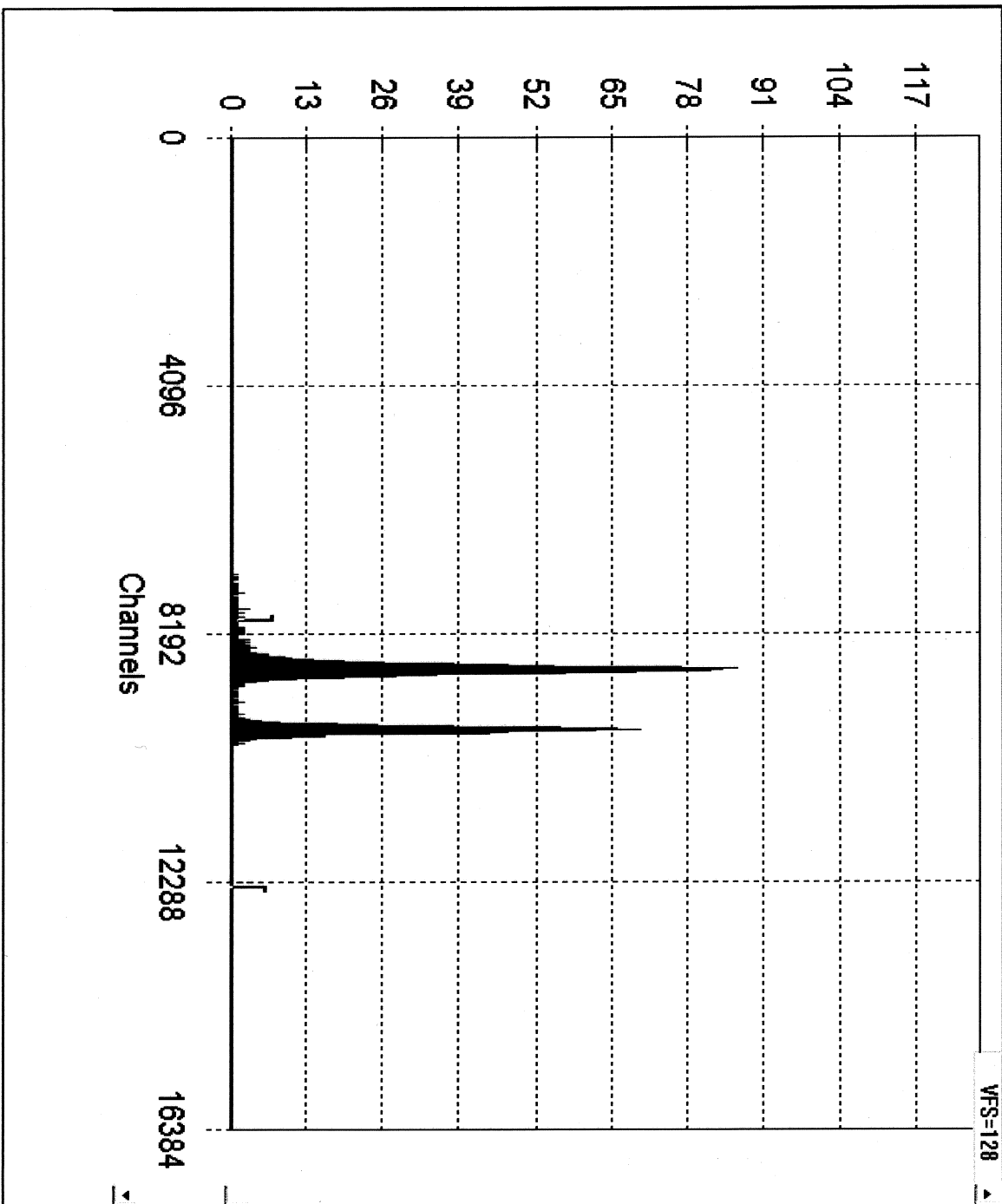
KeV

MIC

T LINE: 83 KeV

STEM: 62.1 KeV

LC: 55 KeV



BIAS VOLTS= V

Leakage

nA

Source
Am 241

Rise Time
 1

Flat Top
 0

Vacuum = 7×10^{-7} Torr

Si-detector Inspection Record

Date: 10/02/2007 **Time:** -6:00 pm

Tel n.: 12 **Inspected detector(s):** dE(2297-2) + E(2113-7)
dE removed

1st inspector: Ulad HENZL

2nd inspector: Daniela HENZLOVA

WIREBONDS STATUS

dE				E-front				E-back			
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1				1				1			
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4				4				4			
5				5				5			
6				6				6			
7				7				7			
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28				28				28			
29				29				29			
30				30				30			
31				31 ↑				31			
32				32 ↓	GR	X	X	32			

Legend: ↑ strips interconnected

X = bond missing

/ = bond broken

~ = bond damaged

Overall detector status:

(e.g. dusty surface, scratches, dirty frame and/or cable, status of telescope can ...)

dE wirebonds look fine

Ej wirebonds look fine

Eb wirebonds look fine

Si-detector Inspection Record

Date: 10/5/2007 **Time:** 8:00pm **Tel n.:** 17
Inspected detector(s): dE(2297-2) + E_F(2113-7)
What occasion: dE part back in can
1st inspector: Vlad HENZL
2nd inspector: Janella HENZLOVA

WIREBONDS STATUS

dE				E-front				E-back			
strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd	strip n.:	1st	2nd	3rd
1				1				1			
2				2				2			
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30				30				30			
31				31				31			
32				32	↓	G12	X X	32			

Legend: ↓ strips indicate checked

X = bond missing / = bond broken ~ = bond damaged

Overall detector status:

(e.g. dusty surface, scratches, dirty frame and/or cable, status of telescope can ...)

By wirebonds look good